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# **2026Q1 Operation Briefing of Nan Ya PCB Corp.**

**June 12<sup>th</sup> 2026**



# Disclaimer

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**The description of historical events might include the information that was not reviewed by accountants. Thus, it might be insufficient to fully exhibit the financial status or operation results of Nan Ya PCB Corp.**

**The actual operation results, financial status, and sales outlook in the future might be different from what will be indicated or implied in this meeting. The reasons may be including but not limited to the market demand, price fluctuation, competition dynamic, global economy, supply-chain, foreign exchange rate, and other risks that the Company cannot control.**

**Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.**



# Agenda

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- **Company Profile**
- **Financial Status**
- **Future Product Development**
- **Operational Strategies in 2026**



# Company Profile

## Business Overview

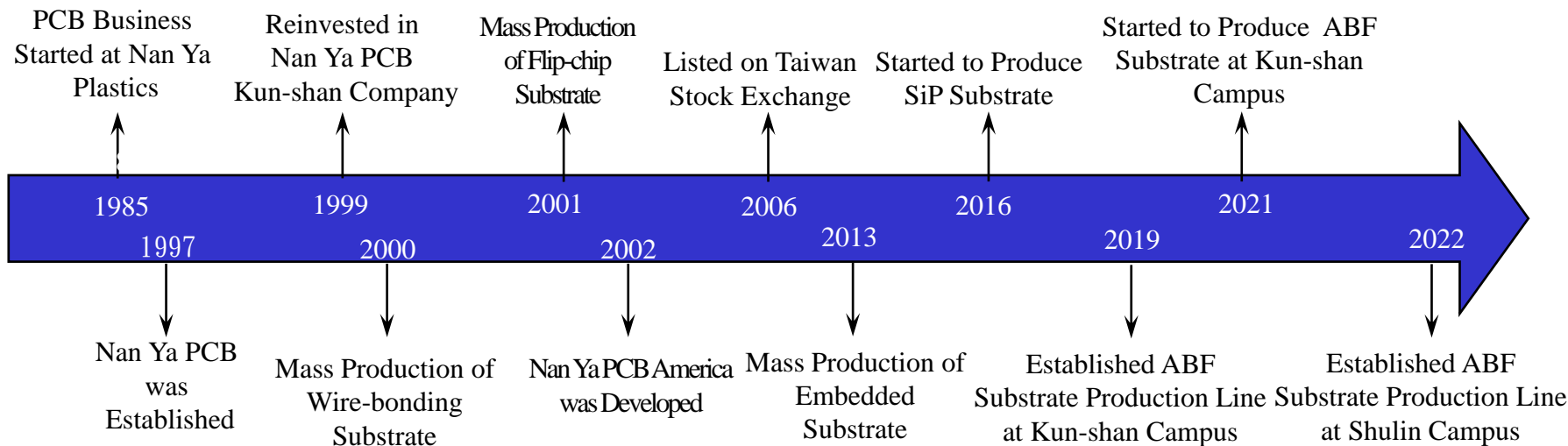
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- **Subsidiary Company of Nan Ya Plastics Corp.**
- **Manufacture and Sell IC Substrates and PCBs**
- **2026Q1 Consolidated Revenues: NTD 11.1 Billion**
- **Market Value: NTD 337.3 Billion(March 31<sup>th</sup> 2026)**
- **Production Locations : Taiwan and China**



# Company Profile

## Milestone



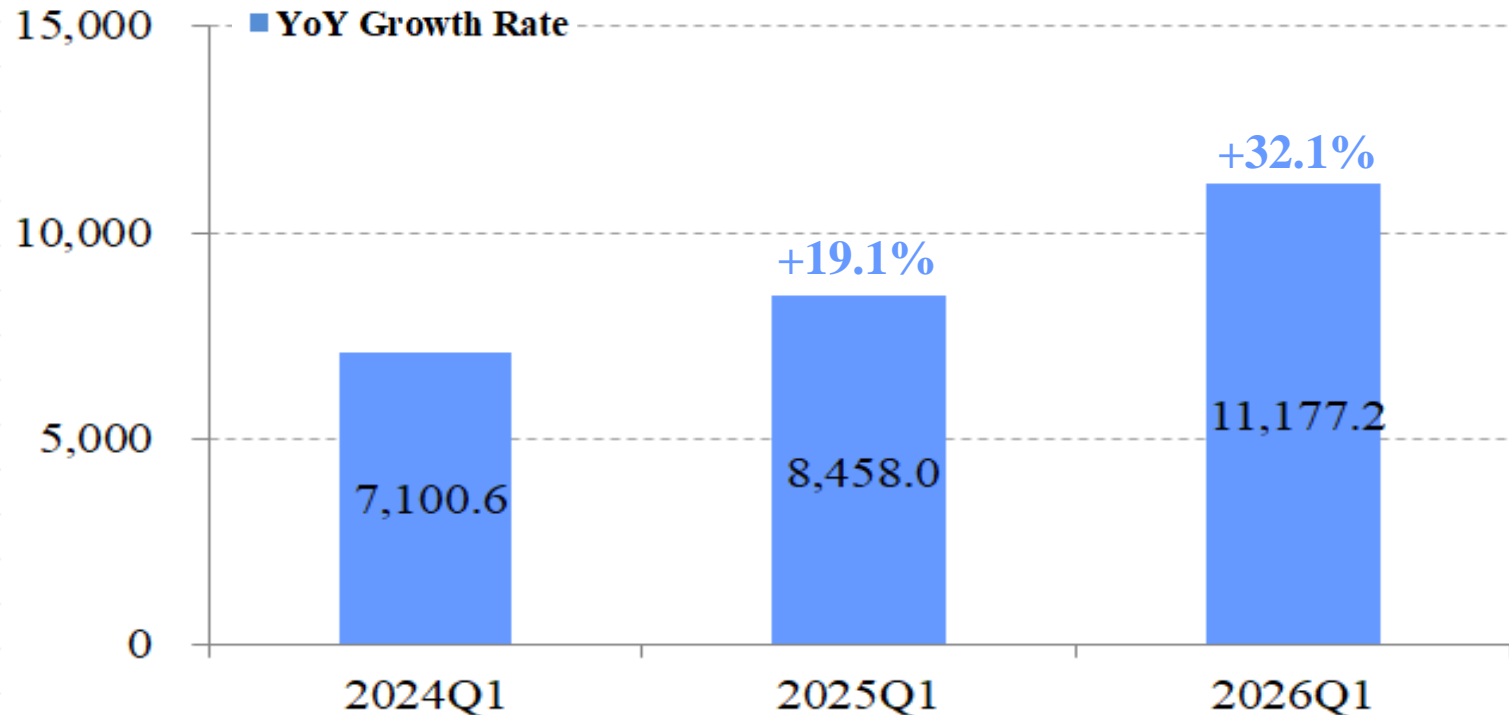
- 1985 : PCB business unit was formed at Nan Ya Plastics Corp. and started manufacturing PCBs
- 1997 : Approved by the Board of Nan Ya Plastics, Nan Ya PCB Corp. was established via reinvestment
- 1999 : Reinvested Nan Ya PCB Kun-shan Company with capital of USD29.8 million
- **2000 : Started manufacturing wire-bonding substrates**
- **2001 : Upgraded technologies and produced flip-chip substrates**
- 2002 : Established Nan Ya PCB America Corp.
- 2006 : Listed on Taiwan Stock Exchange with ticker 8046 TT
- 2013 : Upgraded technologies and produced Embedded substrates
- 2016 : Started to produce System in Package (SiP) substrates
- 2019 : In response to market demand, Nan Ya PCB Corp. started to build ABF substrate production line at Kun-shan Campus
- **2021 : Kun-shan Campus started to manufacture ABF substrates**
- **2022 : Shulin Campus started to manufacture ABF substrates**



# Financial Status

## Consolidated Revenues(IFRS) in Last 3 Years

NTD Million



- **Revenues in 25Q1 were 19.1% greater than those in 24Q1:**

Higher demand for high-end server, 800G switch, and enterprise SSD IC substrates drove YoY revenue growth in 25Q1.

- **Revenues in 26Q1 were 32.1% greater than those in 25Q1:**

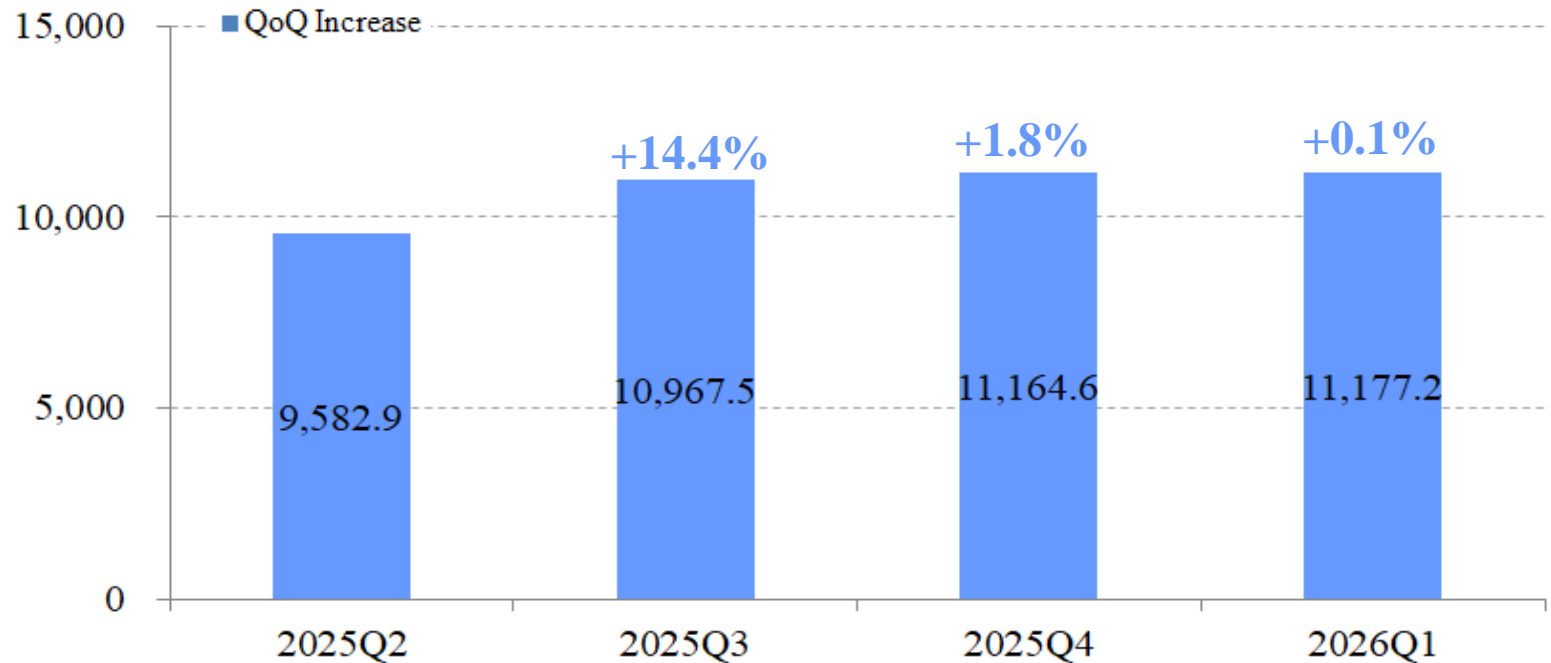
Sustained data center demand and increased high-end IC substrate sales drove further YoY revenue growth in 26Q1.



# Financial Status

## Quarterly Consolidated Revenues(IFRS) in a Year

NTD Million

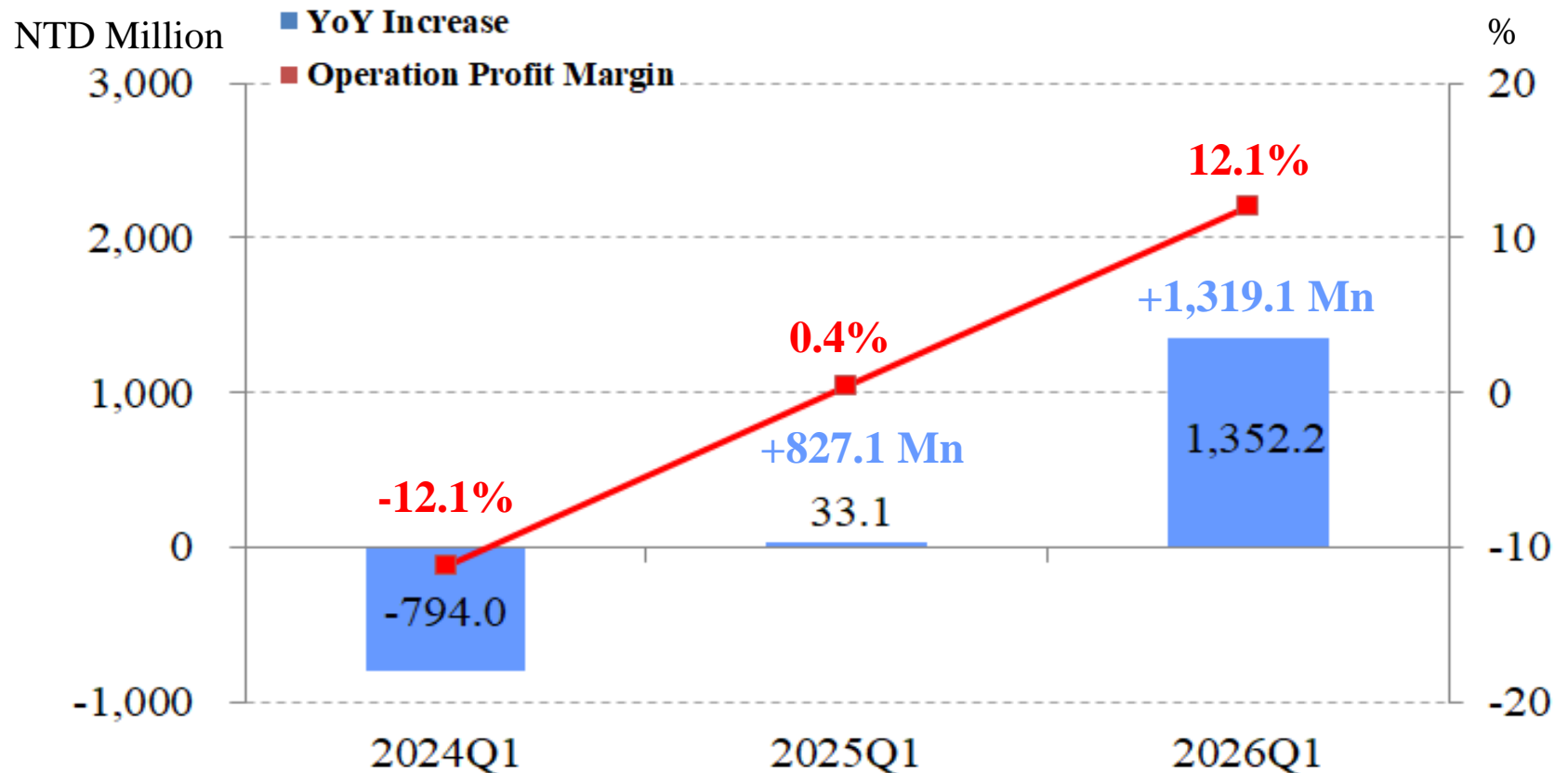


- **Revenues in 25Q3 were 14.4% greater than those in 25Q2:**  
Solid growth in cloud application products and a recovery in memory demand led to a further increase in revenue of 25Q3.
- **Revenues in 25Q4 were 1.8% greater than those in 25Q3:**  
Driven by increased demand for high-end servers and switches, revenue in the fourth quarter increased compared to the third quarter.
- **Revenues in 26Q1 were 0.1% greater than those in 25Q4:**  
High-end IC substrate demand offset fewer working days, driving 26Q1 revenue above 25Q4 levels.



# Financial Status

## Operation Profits(Losses) in Last 3 Years

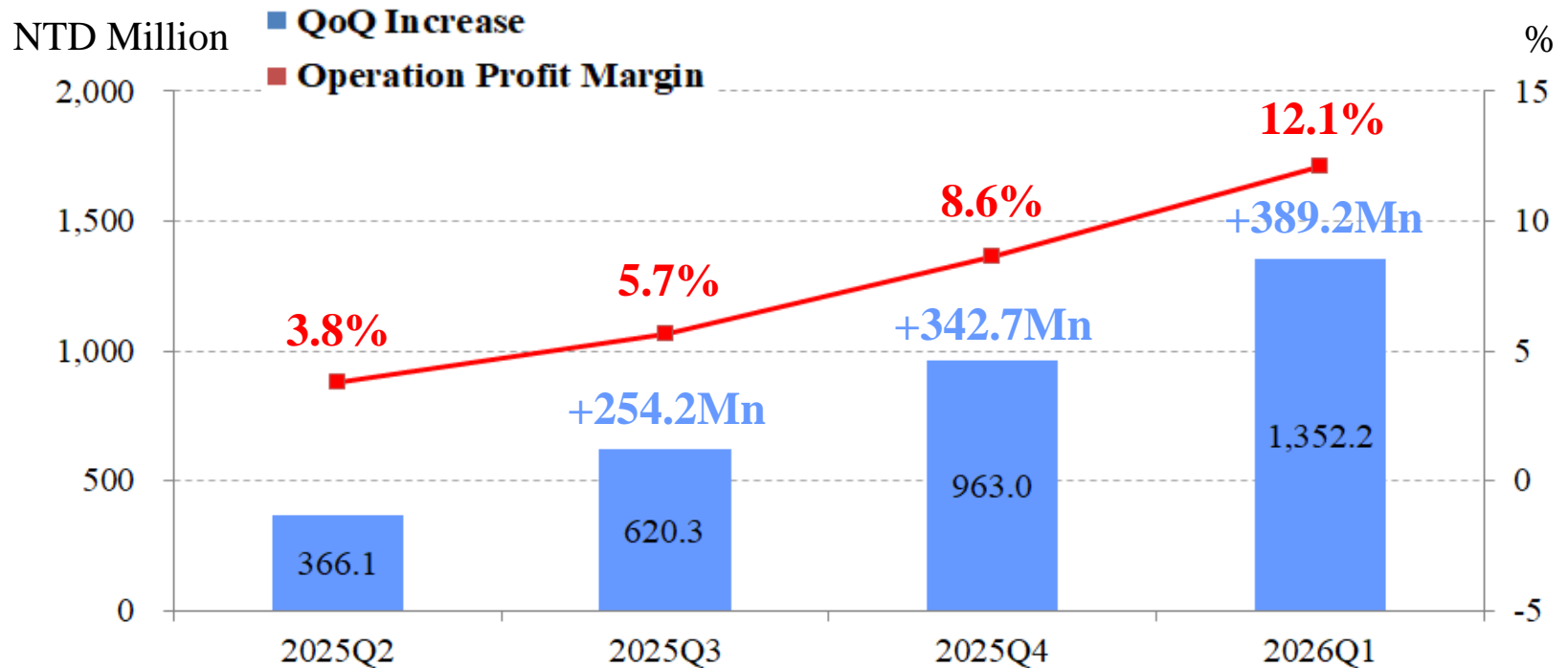


- **Operation profits in 25Q1 were increasing NTD 827.1 Mn from 24Q1:**  
Robust high-end networking demand and a better product mix boosted operating profit.
- **Operation profits in 26Q1 were increasing NTD 1,391.1 Mn from 25Q1:**  
Rising demand for high-end servers, switches, and memory fueled operating profit growth.



# Financial Status

## Quarterly Operation Profits in a Year

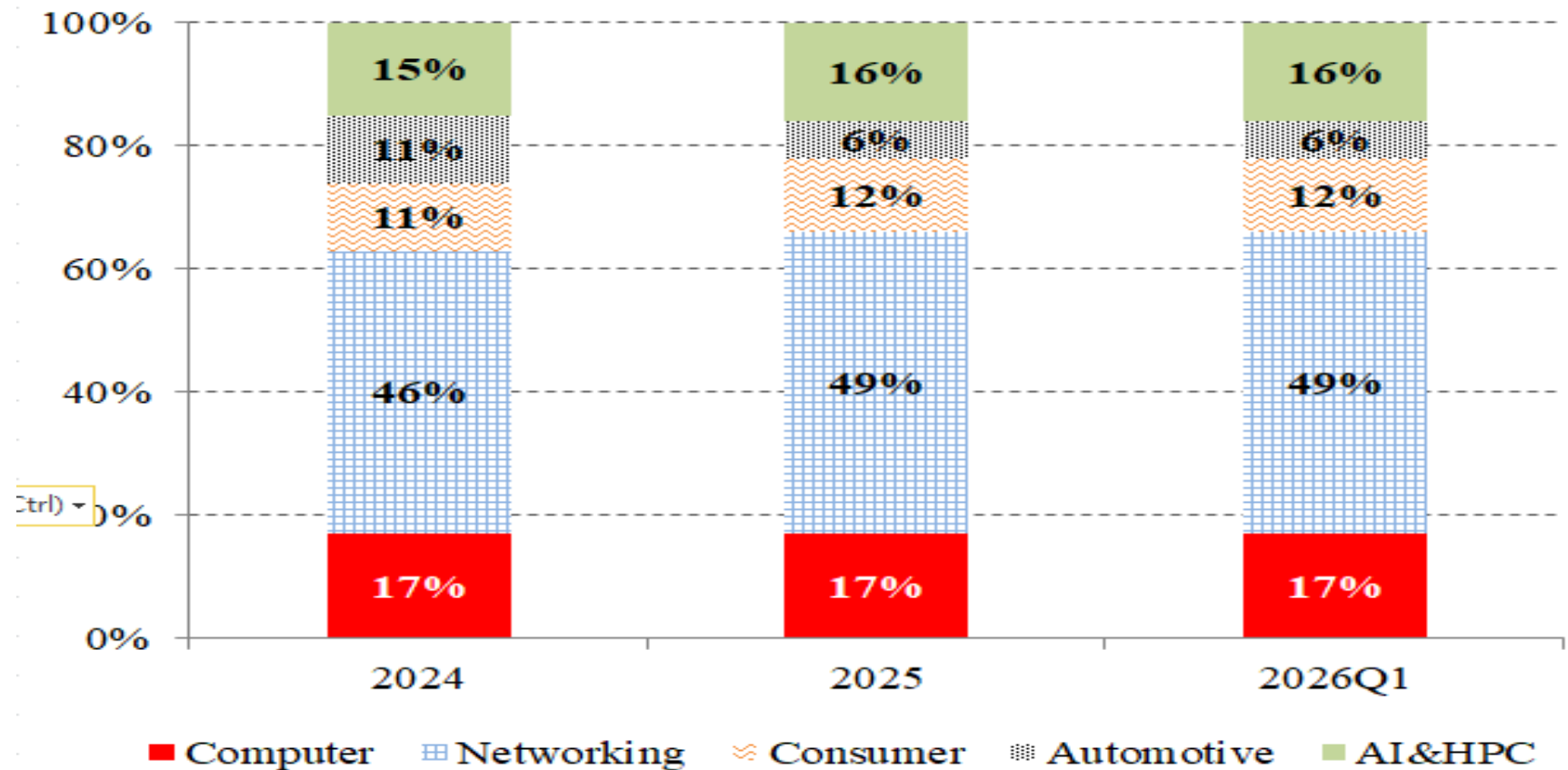


- **Operation profits in 25Q3 were increasing NTD 254.2 Mn from 25Q2:**  
Demand for data center and memory products increased, leading to a rise in operating profit in 25Q3 compared to 25Q.
- **Operation profits in 25Q4 were increasing NTD 342.7 Mn from 25Q3:**  
With an rising demand for high-end servers and switches, operating profit in the fourth quarter increased compared with the third quarter.
- **Operation profits in 26Q1 were increasing NTD 389.2 Mn from 25Q4:**  
Driven by steady demand in server and switch IC substrates, 26Q1 operating profit saw quarterly growth.



# Financial Status

## Revenue Structure(By Applications)

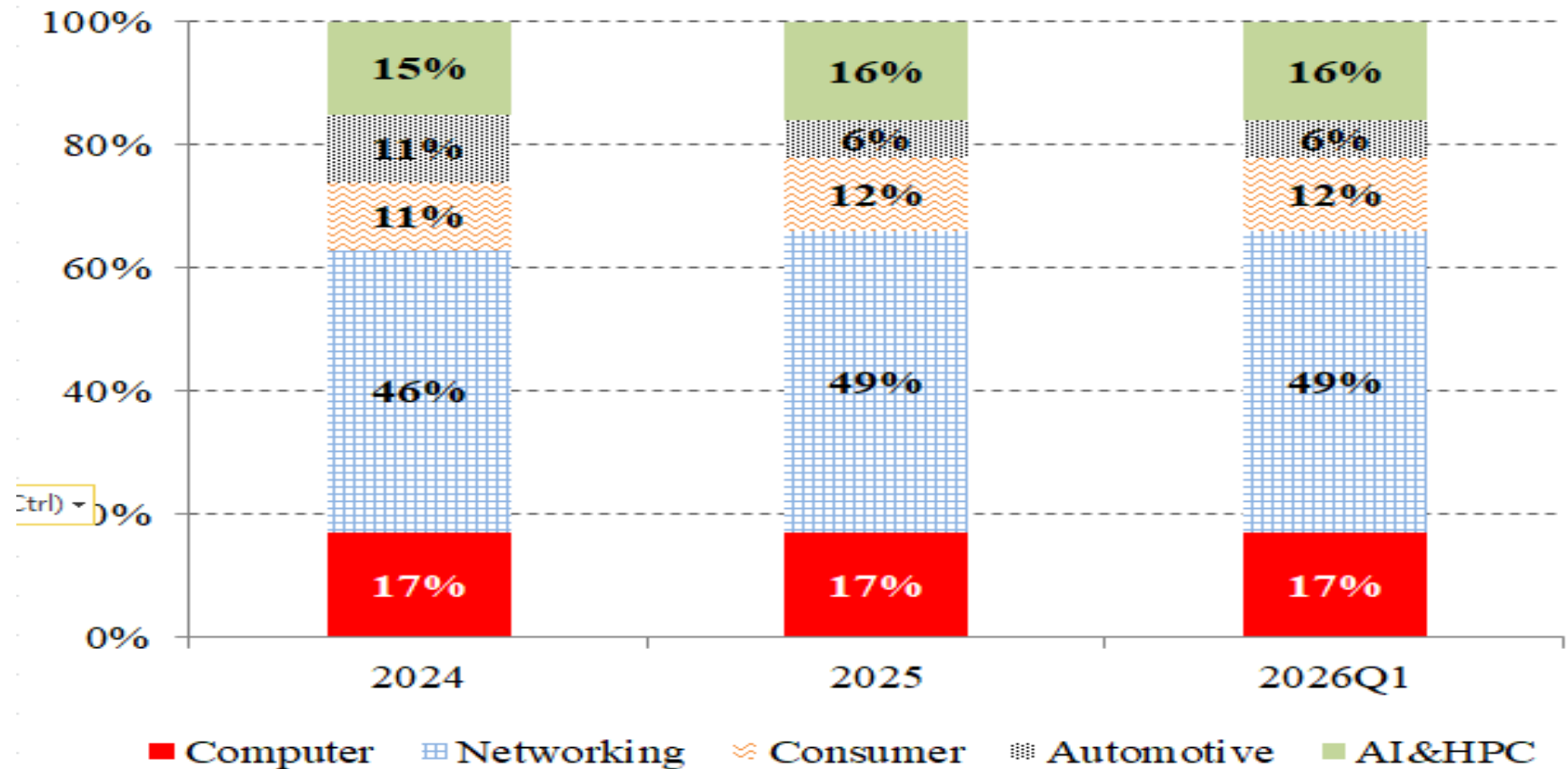


- Impacted by component shortages, sales growth for PCs and consumer electronics was constrained. Consequently, our revenue contribution from related applications in 26Q1 was on par with 2025.
- The ongoing high-end switch upgrade trend in data centers kept our networking revenue contribution elevated through 26Q1.



# Financial Status

## Revenue Structure(By Applications)



- With automotive demand remaining weak and supply chains affected, our 26Q1 revenue contribution from automotive electronics applications was on par with 2025.
- Driven by steady data center demand for AI and HPC, our 26Q1 revenue contribution from these applications was on par with 2025.



# Future Product Development

## Continue to Expand High Value Products

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### ■ ABF Substrate

As hyperscalers continue to expand data center Capex, we are collaborating closely with customers to develop next-generation substrates for AI server ASICs. Additionally, we are developing substrates for high-end switches and routers to meet high-speed data transmission needs and increase our share of high-value products.

### ■ BT Substrate

Beyond developing substrates for next-gen 5G antenna modules, smart glasses, and SSD controllers, we are partnering with customers on next-gen server and Power IC substrates. These solutions address the high-efficiency power requirements of AI chips and are set to enhance our profitability.

### ■ Conventional PCB

To capitalize on rising server and switch demand, we are mass-producing high-end PCBs, including server network cards, backplanes, and high-layer switch boards. We are also expanding into Edge AI with high-end PC and LED PCBs to enhance product diversification.



# Operational Strategies in 2026

## Implementing 4 Major Transformations

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- **Product Transformation:** Continuously expanding the sales mix of cloud computing, edge computing, and high-speed transmission products to foster a higher-value and more diversified product portfolio.
- **Business Transformation:** Develop new materials, technologies, and products to strengthen the Company's capabilities.
- **Digital Transformation:** Leverage digital technologies to enhance AI and digital transformation, achieving intelligent operations.
- **Low-Carbon Transformation:** Expand the use of green energy, commit to energy conservation and carbon reduction, and implement the promotion of a circular economy.



Thank You

